



SCIENTECH

# Sciencetech Corp (3583:TT)

M.T. Hsu 2026/03/18

- **This Presentation contains certain forward-looking statements that are based on current expectations and are subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements.**
- **Except as required by law, we undertake no obligation to update any forward-looking statements, whether as a result of new information, future events or otherwise.**

# Agenda



# About Us

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Overview | Milestones | Location | Organization





## Product and Technology

- Equipment Design and Manufacturing
- Wafer Reclaim
- Representative



## Industries We Serve

- Semiconductor (Front-End and Advanced Packaging)
- Compound Semiconductor
- LED / Mini LED / Micro LED
- Flat Panel Display (TFT-LCD, AMOLED, Touch Panel)



**Established:**  
1979  
Taipei, Taiwan

**Capital:**  
US\$ 27 Million  
TWSE:3583

**Employees:**  
>1,070  
(Worldwide)

# Employees

## Over 1,070 Employees

### Representative

- 145 in Taiwan
- 130 in China
- 70% in Service and Process Support

### Equipment Design and Maf'g

- 400 in Total
- 130+ in R&D, Process and Design

### Wafer Reclaim

- 310 in Total

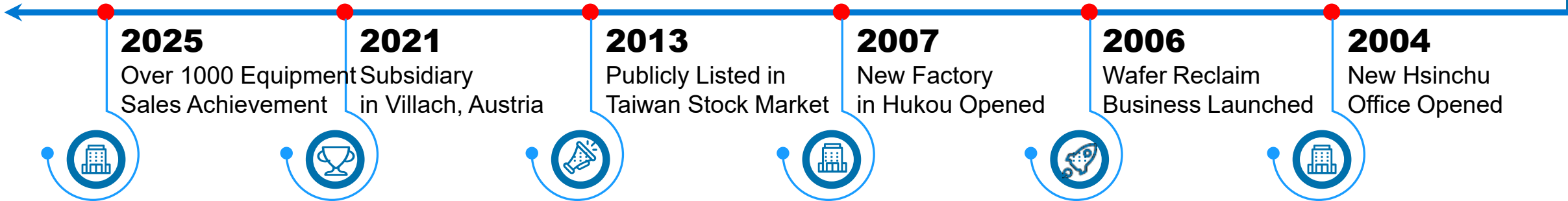
### Administration

- 85 in Total

# Milestones



SCIENTECH  
**1979**



# Locations - Taiwan

Taipei Headquarter

HsinChu Office

HuKou Factory

- Equipment Design and Manufacturing
  - ◆ Equipped With Class 10/1,000/10,000 Clean Room
- Wafer Reclaim



Taichung Office

Chiayi Office

Tainan Office

Kaohsiung Office

# Locations - Worldwide

## Europe

Villach, Austria (2020)

- Sales and Service Office to support European customers
- Interface with our factory and European Customers
- New Product / PRODUCTS Development

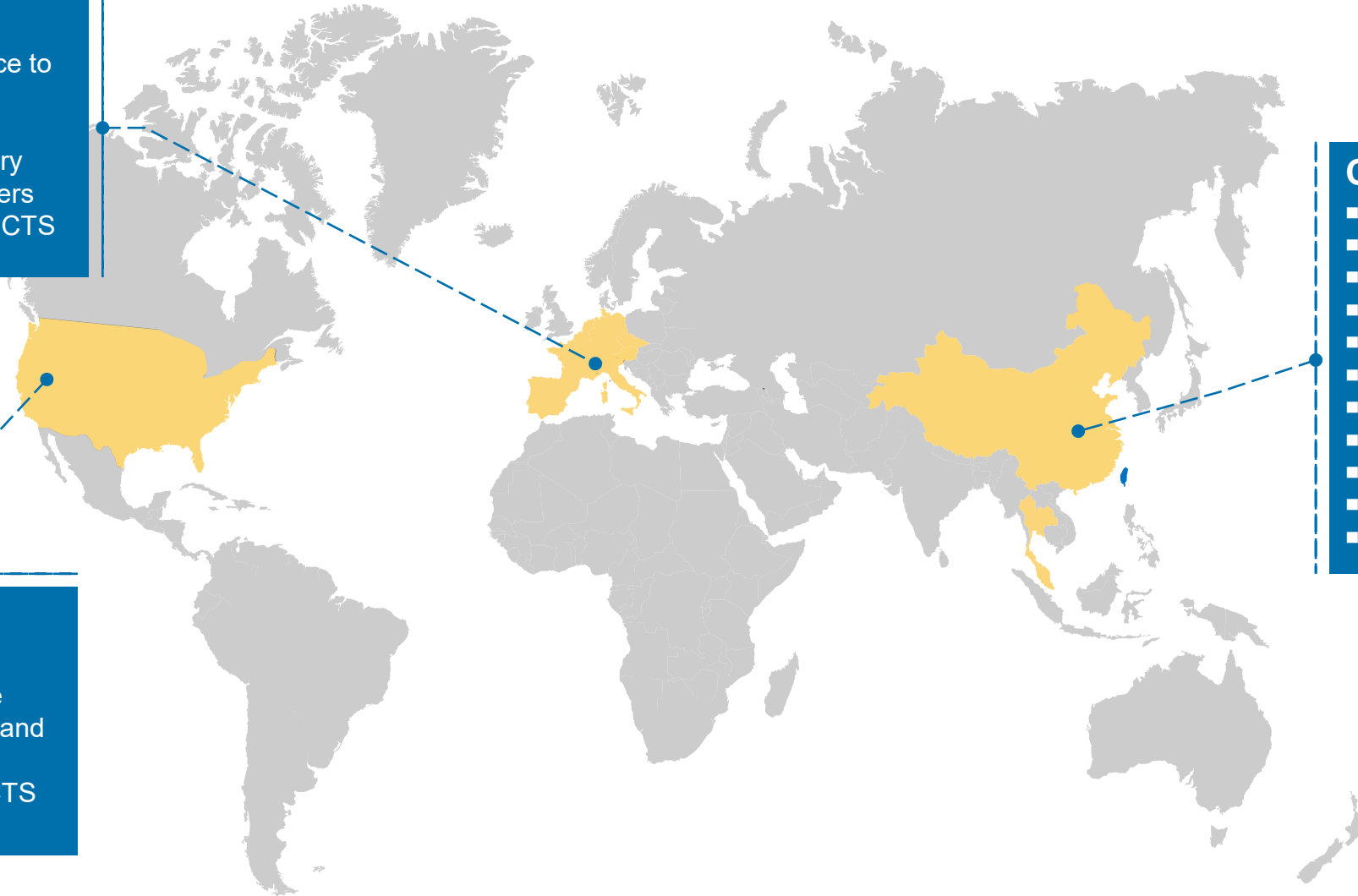
## USA

Santa Clara, CA (1994)

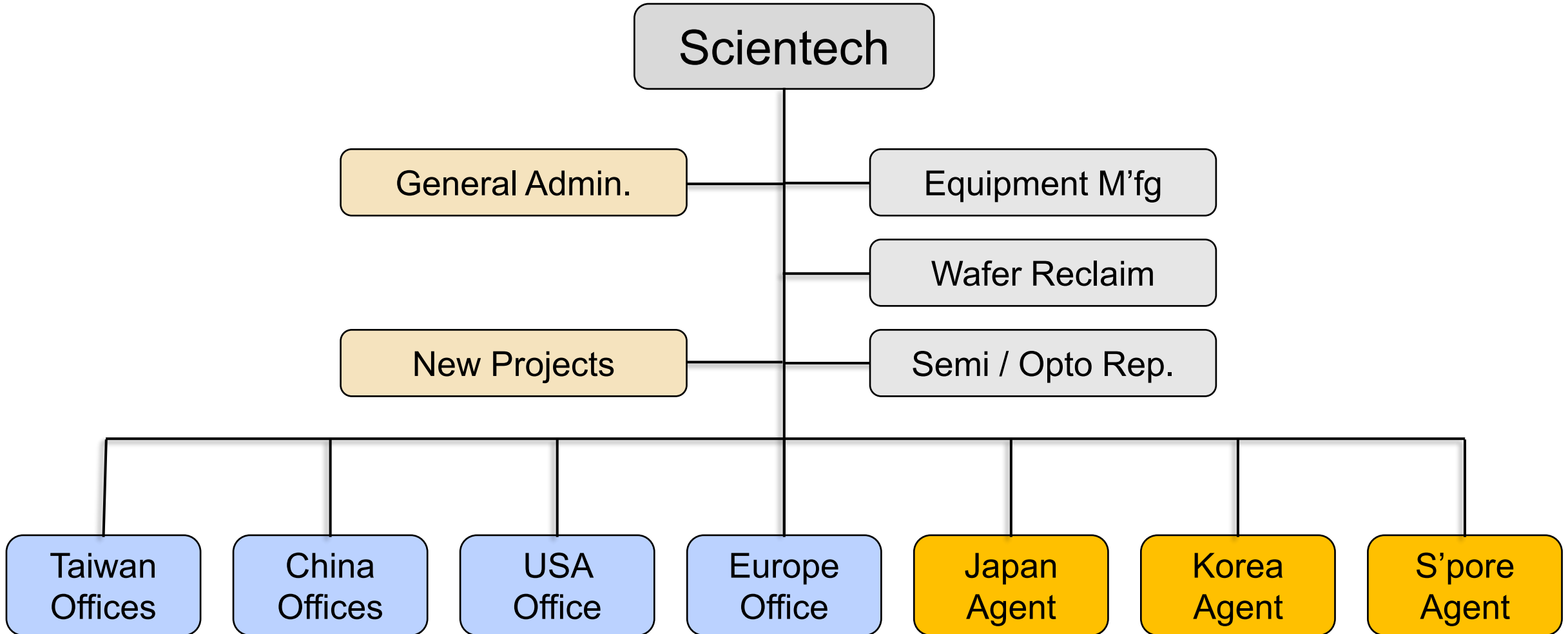
- Sales and Service Office
- Interface with Principals and U.S. Customers
- New Product / PRODUCTS Development

## China

- Beijing office (2004)
- Dalian office (2012)
- Xian (2013)
- Chongqing office (2010)
- Changzhou (2012)
- Wuxi office (2003)
- Shanghai Office (2001)
- Wuhu office (2013)
- Xiamen office (2011)
- Huizhou office (2013)
- Qunming Office (2002)



# Organization



# Products & Services

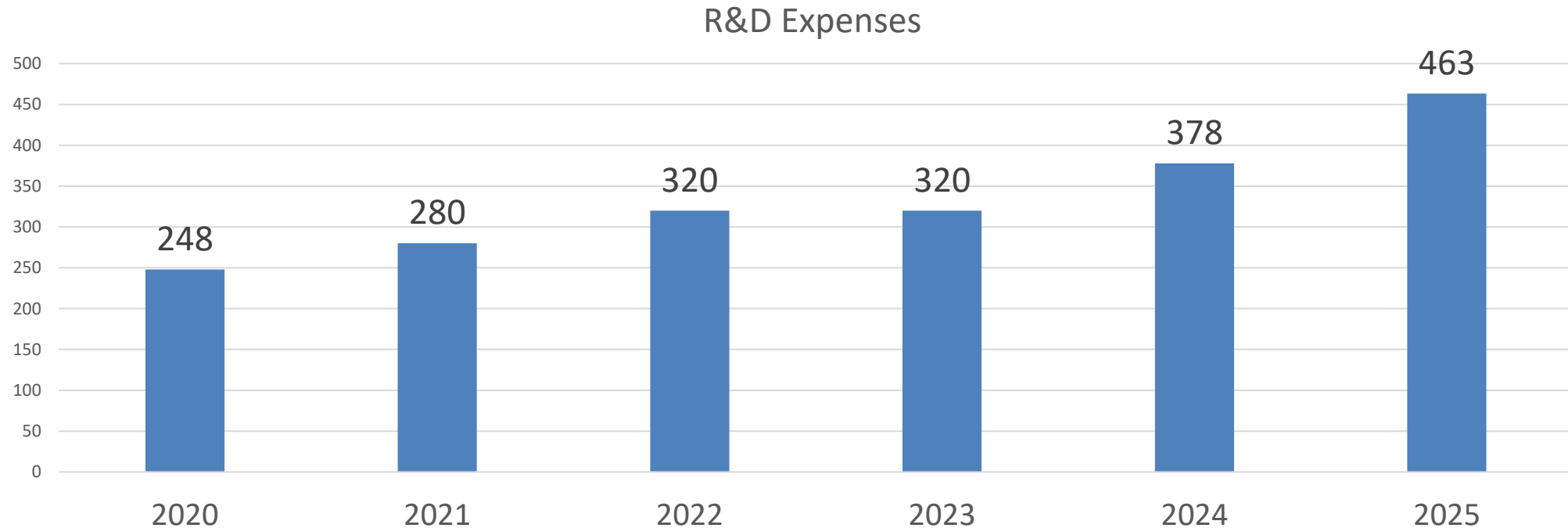
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Equipment Manufacturing and Design | Wafer Reclaim  
| Representative

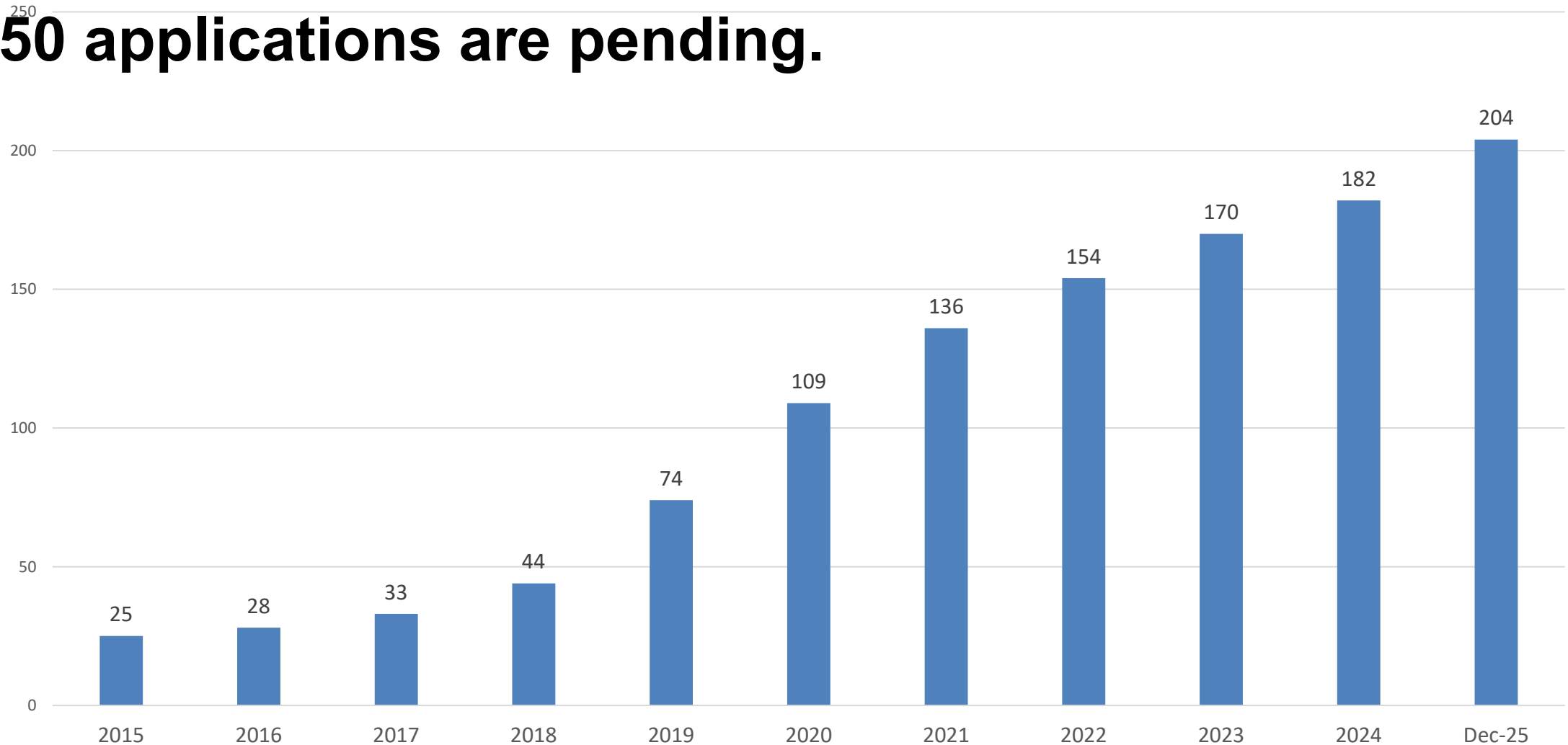


# R&D Expenses

Units NT \$ M	2020	2021	2022	2023	2024	2025
R&D Expenses	248	280	320	341	378	463
Expenses as % of Revenue	6.9%	6.0%	5.7%	4.9%	3.9%	4.1%
<b>Expenses as % of Manufacturing</b>	<b>16.5%</b>	<b>14.9%</b>	<b>15.3%</b>	<b>15.7%</b>	<b>11.3%</b>	<b>9.8%</b>



- The cumulative number of patents on file is 204, and 50 applications are pending.





## Equipment Design and Manufacturing

- Advanced Package
- FEOL
- Mask
- Compound
- etc...



## Wafer Reclaim

- 12" Si Wafer



## Representative

- Equipment/Metrology
- Sub-System
- Material
- Repair and Refurbish

# Wafer Reclaim Service

## Advanced Clean Technology

- 19nm Particle
- Low Trace Metal (<1E9)



## Advanced Defect Inspection (SP1/SP2/SP5/SP7)

## 12" Si Wafer

- Capacity: 210K / Month
- Cu and Non-Cu Process



Cleaning

Etching

**Full Process Optimization**

## Capacity Expansion

- Additional 40K / Month by end of 2026



Polishing

Grinding

## Complete Polishing Process

- Single/Double Side Polish
- Final Haze Polish

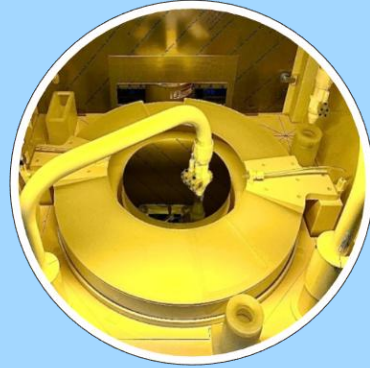


## Super Flatness (GBIR < 0.5mm)

# Equipment Design & MFG



**Wet Bench**



**Wet Single Wafer**



**TBDB**



**Baking**

## Wet Process – Bench

### Application

- Semiconductor: FEOL, BEOL, Compound
- Advanced Packaging/Bumping...

### Features

- Cassette type or Cassette-less type
- Adopted by big international companies
- Leading-edge technologies

### Process

- Etch: Metal/Oxide/Nitride remove
- Stripper: PR/PI strip, Polymer remove
- Clean: Pre/Post/Flux clean
- Electro-less Plating: Zn/Ni/Pd/Au



## Wet Process – Single Wafer

### Application

- Semiconductor: BEOL, FEOL, Compound
- Advanced Packaging/Bumping

### Process

- UBM / Metal Etch
- Flux Clean (Hot DIW)
- PR Strip
- Wafer Clean (APC, Soft spray)
- Final Clean/Mask Clean/Frame Clean

### Features

- Soak/Immersion + Single
- Adopted by big international companies
- Leading-edge technologies



## Temporary Bonding De-Bonding



### Application

- IGBT & SiC Power Device
- Advanced Packaging for Semiconductor



### Features

- User-friendly graphical user interface
- Adopted by big international companies
- Leading-edge technologies



### Process

- Temporary Bonding
- Temporary De-bonding
- Release Layer Coating
- Carrier (Glass) Recycling



## Moisture Baking

### Application

- Semiconductor: BEOL
- Advanced Packaging for Semiconductor

### Features

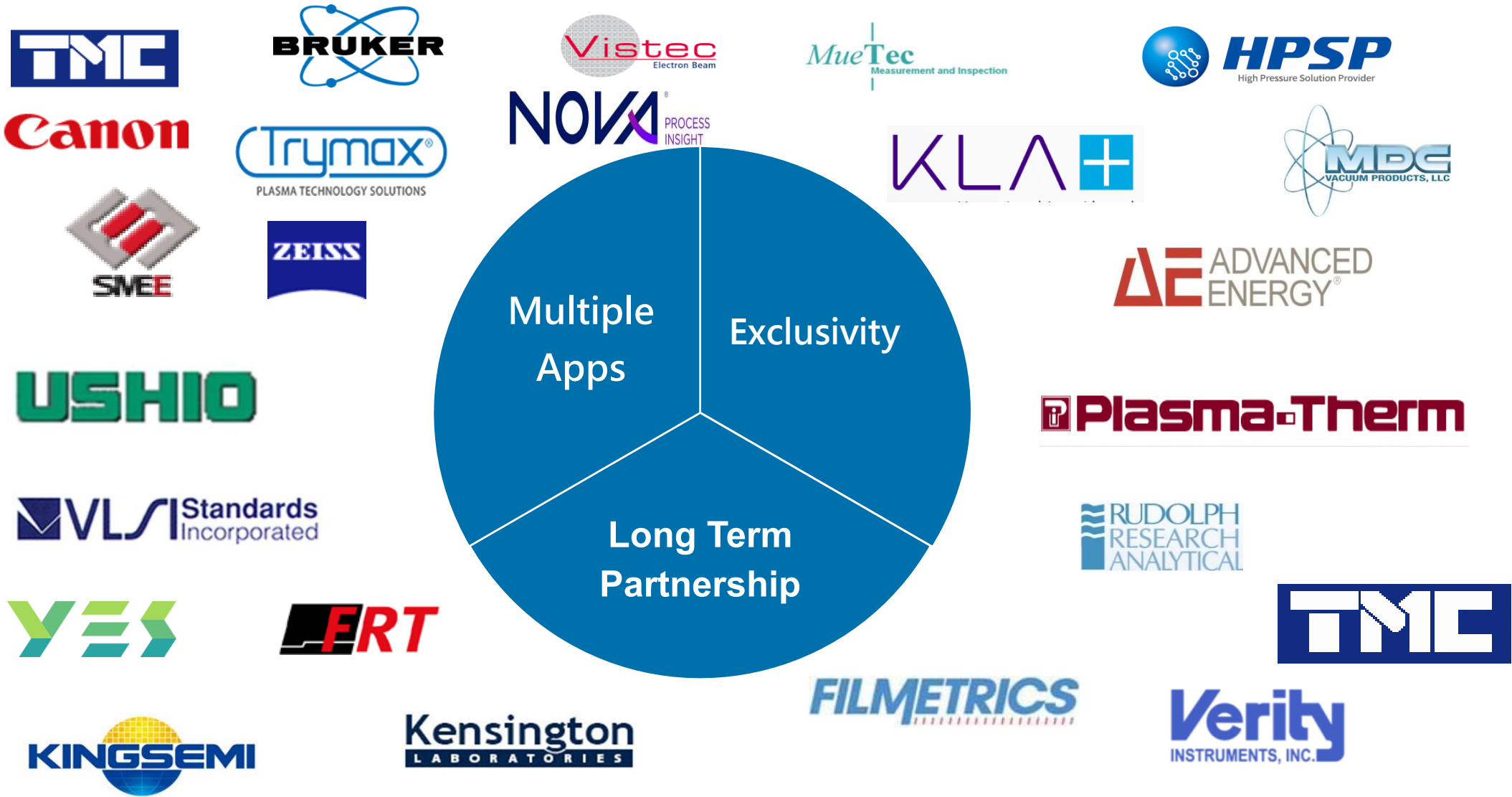
- Availability for horizontal or vertical process
- High precision temperature control
- Weight handling capacity up to 23kg per lot

### Process

- Pre-underfill baking
- Pre-mold baking
- DFR Hard Bake



# Trading (Agent/Distributor)



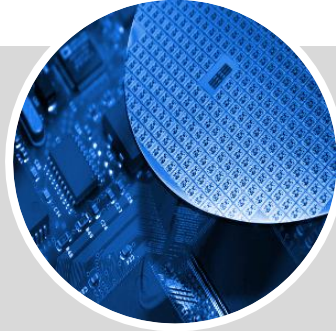
# Representative Product Lines



Lithography



Etch



Thin Film



Diffusion



# Representative Product Lines



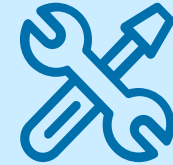
## Metrology



## Sub-Systems



## Package & Material



## Robot Repair and Refurbish



# Corporate Governance

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# Certificates



## Sustainability Report Officially Released since 2024/08



**Eco-Friendly Manufacturing**



**Safe And Warm Working Environment**



**Operating With Integrity**



**Contributing To Society**

**SEMICON<sup>®</sup>**

**Semicon China**

Mar. 26-28, 2025  
Shanghai

**SEMICON<sup>®</sup>**

**Semicon TW**

Sep. 10-12, 2025  
Taipei

**SEMICON<sup>®</sup>**

**Semicon West**

Oct. 07-09, 2025  
Phoenix

**SEMICON<sup>®</sup>**

**Semicon Europa**

Nov. 18-21, 2025  
Munich

# Exhibition



**ISES**

May 13-14, 2025  
Taipei



**ECTC**

May 27-30, 2025  
Dallas, Texas

# Financial Results

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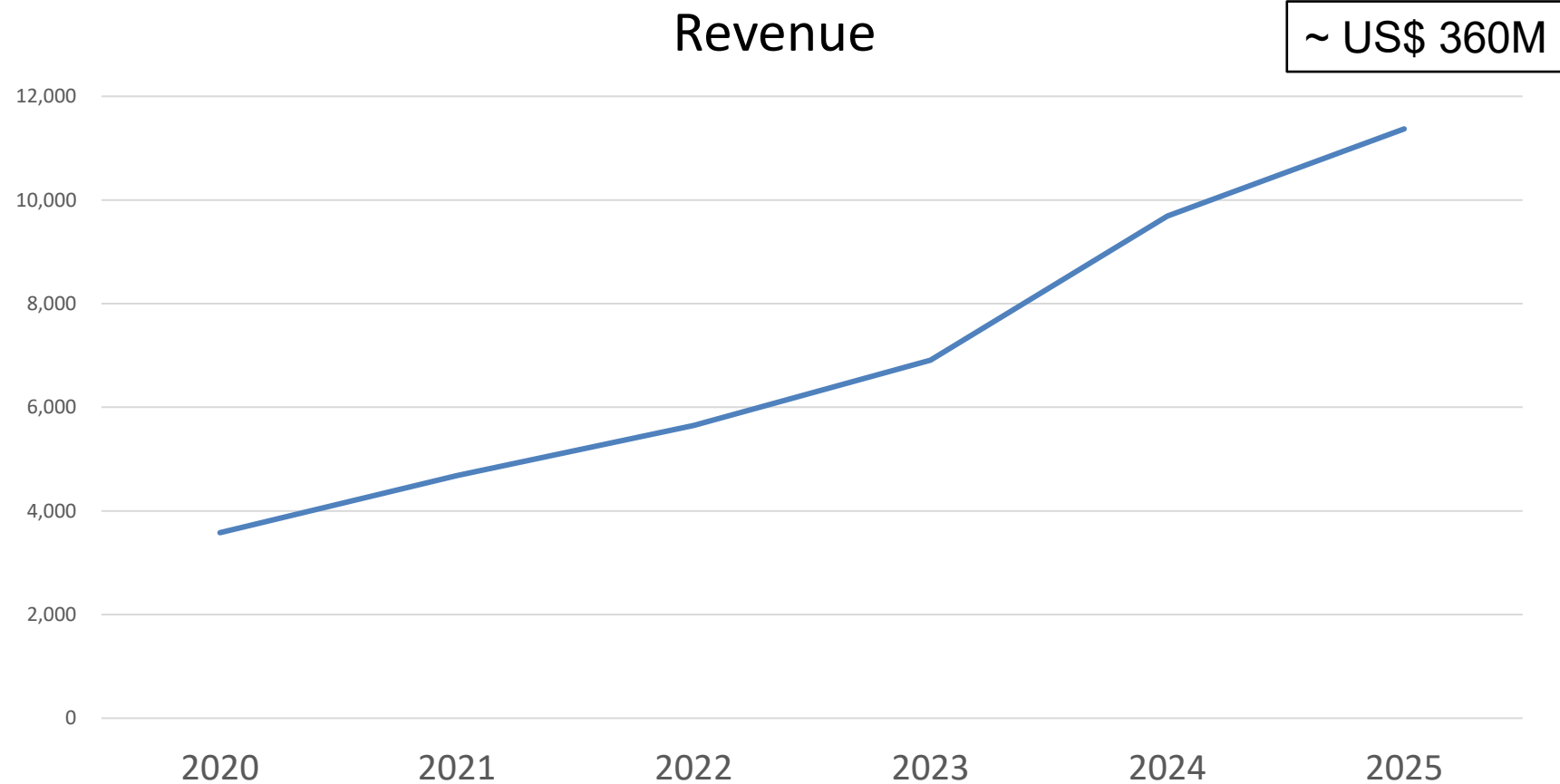


# Income Statement

Units : NT \$ M	2020	2021	2022	2023	2024	2025
Revenues	3,580	4,684	5,650	6,911	9,688	11,371
Gross Profit	1,456	1,667	2,084	2,201	2,906	3,814
Operating Expenses	991	1,112	1,374	1,483	1,790	2,238
Operating Income	465	555	710	718	1116	1,576
Income Before Tax	389	524	736	860	1277	1,540
Net profit attributable to:Owners of the Company	305	420	568	650	927	1,110
<b>EPS</b>	<b>3.80</b>	<b>5.23</b>	<b>7.08</b>	<b>8.10</b>	<b><u>11.54</u></b>	<b><u>13.82</u></b>
Gross Margin	41%	36%	37%	32%	30%	34%
Operating Margin	13%	12%	13%	10%	12%	14%
Income Before Tax Margin	11%	11%	13%	12%	13%	14%

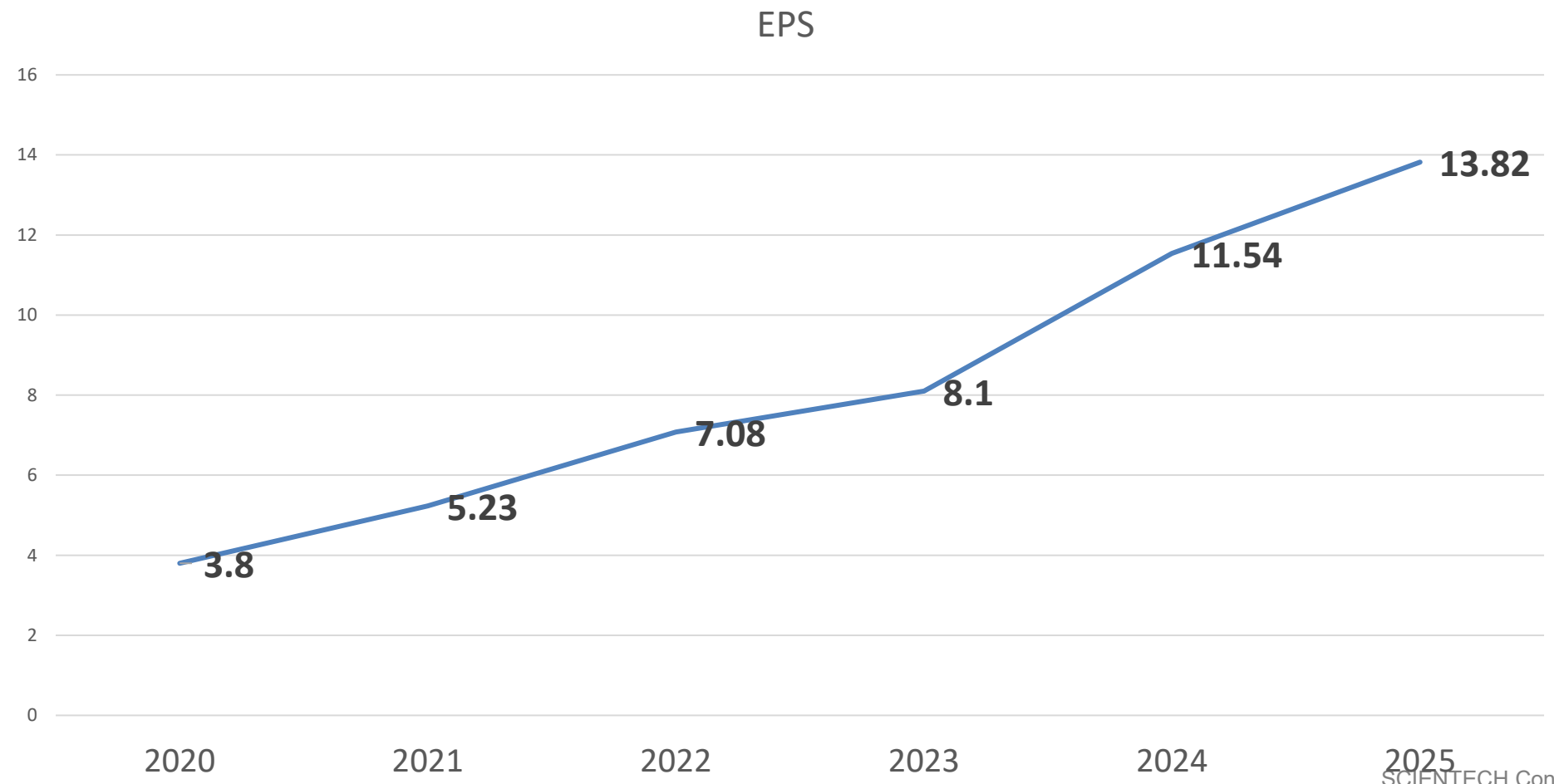
# Annual Revenue

Units NT \$ M	2020	2021	2022	2023	2024	2025
Revenue	3,580	4,684	5,650	6,911	9,688	11,371



# EPS

UNIT : NTD	2020	2021	2022	2023	2024	2025
EPS	3.80	5.23	7.08	8.10	11.54	13.82

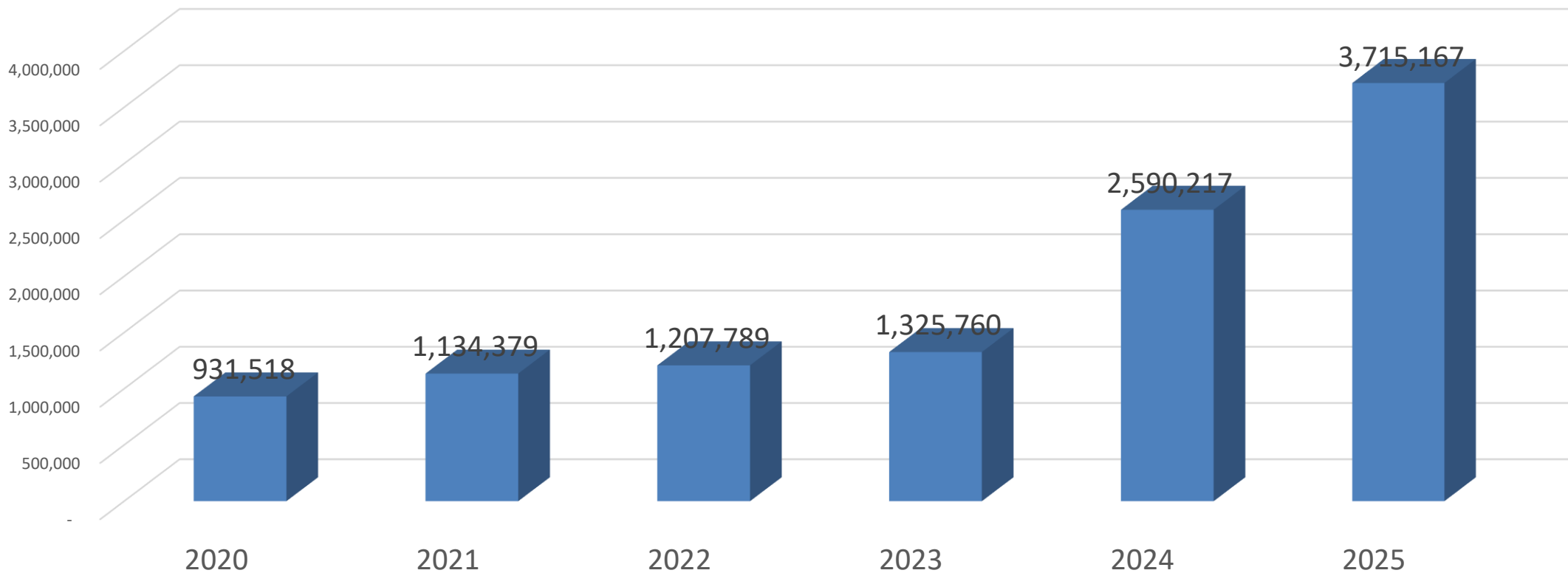


# Equipment Revenue



SALES	2020	2021	2022	2023	2024	2025	2026
Equipment	931,518	1,134,379	1,207,789	1,325,760	2,590,217	3,715,167	

Equipment

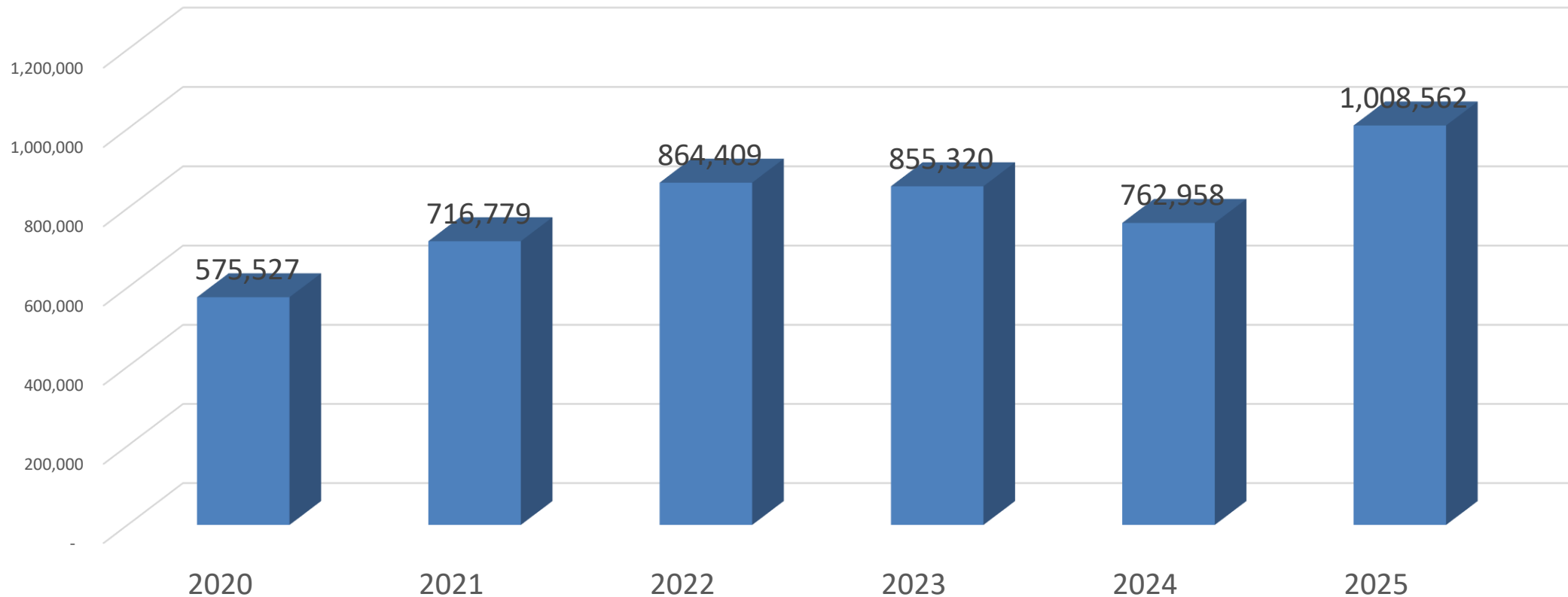


# Wafer Reclaim Revenue



SALES	2020	2021	2022	2023	2024	2025	2026
Wafer Reclaim	575,527	716,779	864,409	855,320	762,958	1,008,562	

Wafer Reclaim

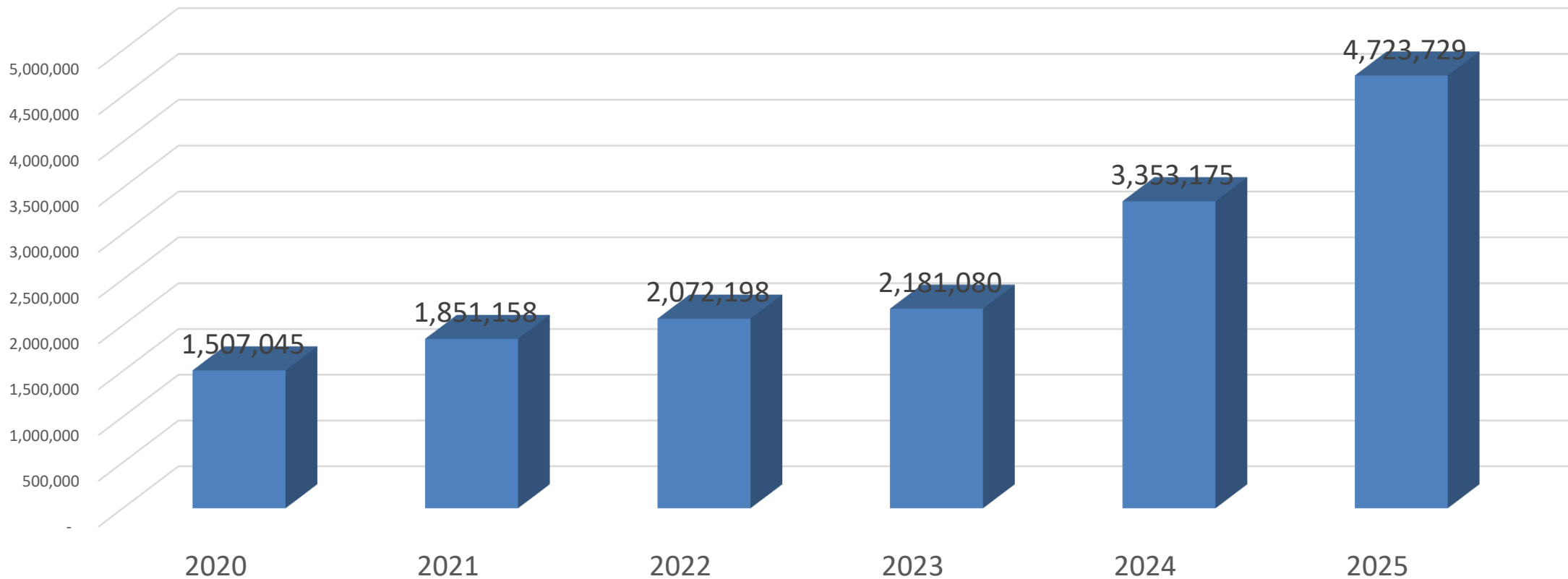


# Manufacturing Revenue



SALES	2020	2021	2022	2023	2024	2025	2026
Manufacturing	1,507,045	1,851,158	2,072,198	2,181,080	3,353,175	4,723,729	

Manufacturing

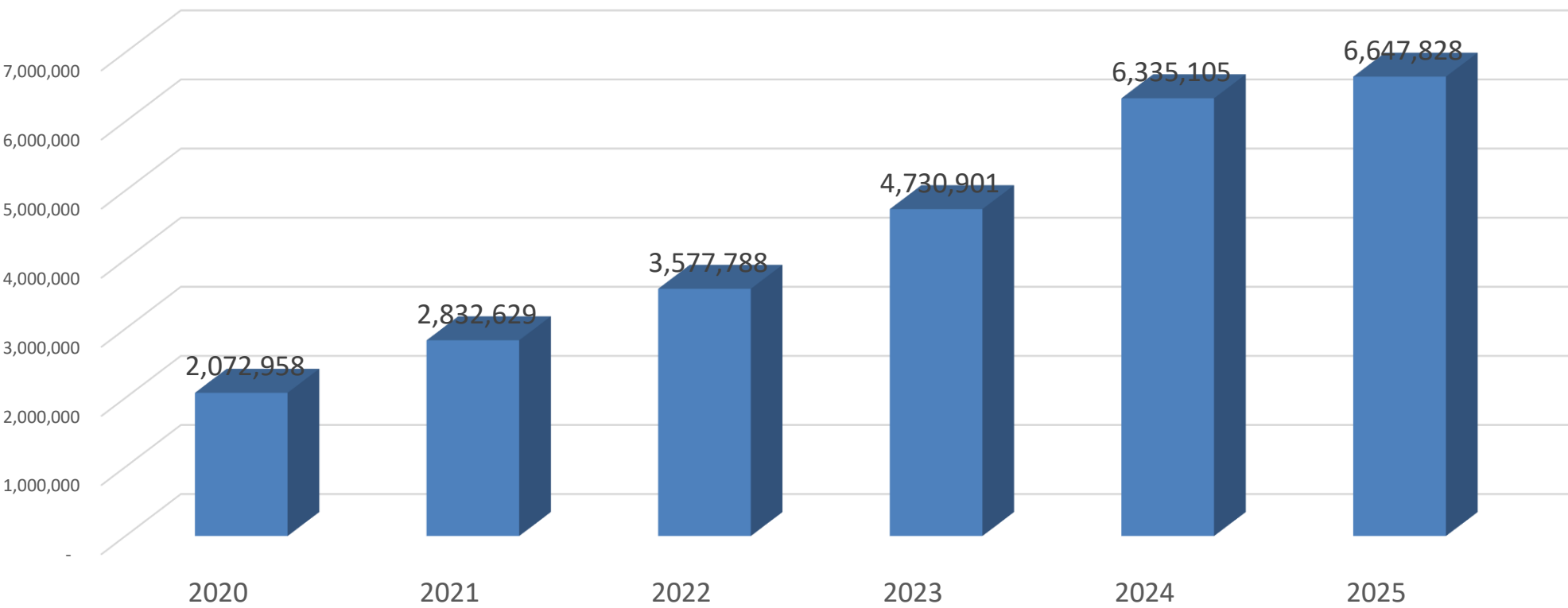


# Trading Revenue



SALES	2020	2021	2022	2023	2024	2025	2026
Trading	2,072,958	2,832,629	3,577,788	4,730,901	6,335,105	6,647,828	→ ??

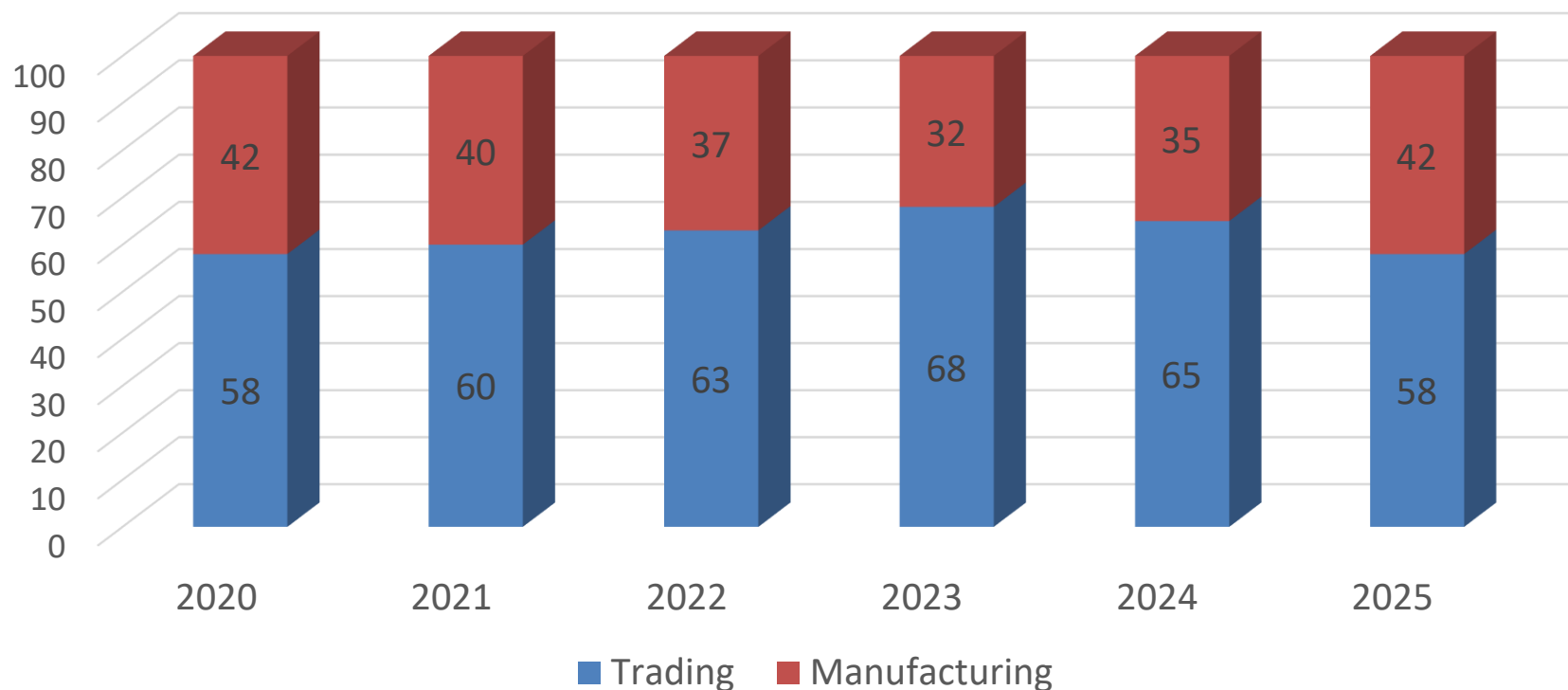
Trading



# Products Mix – Revenue



Units : %	2020	2021	2022	2023	2024	2025	2026	Gross Margin
<b>Trading</b>	58	60	63	68	65	58%	<50%	Below Average
<b>Manufacturing</b>	42	40	37	32	35	42%	>50%	Above Average



# Future Outlook

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# Expansion Roadmap

- 2023: New equipment production base in Hukou (off-site)
- 2024: Expansion of existing equipment production at Hukou Plant
- **2025 Q4: Wafer Reclaim Capacity 50K/Month at Hukou Plant**
- **2026 Q1: New Office in Shanghai**
- **2026 Q4: 9,000 M<sup>2</sup> (2,700坪) new building (Plant II) for EQPT MFG, and Warehouse next to Hukou Plant (Plant I)**
- **2026 Q4: Wafer Reclaim Capacity 40K/Month at Hukou Plant**
- **2027 Q4: 22,000 M<sup>2</sup> (6,600坪) new building for EQPT MFG, Office and Warehouse in Tainan (southern Taiwan)**
- 2027: Wafer Reclaim Capacity 50K/Month at Hukou Plant

# Key Highlights

- **Semiconductor CAGR to support our aggressive investment.**
- **Semiconductor Market Size**
  - **2024: 640B**
  - **2025: 750B**
  - **2026: 900B – 1Trillion**
- **TSMC's earning call:**
  - **CAGR for AI Accelerator Chips raised from mid-40% to mid-to-high 50% range during 2024-2029**
  - **Total revenue CAGR raised from 20% to 25% during 2024 to 2029**

# Key Highlights

- **YAYATECH (亞亞), AMC (山太  
士 Share 1,282K, 3.78%)**
- **Equipment Capacity (US\$1M  
and above per tool)**
  - 2024: 100
  - 2025: 150
  - 2026: 200
  - 2027: 250
  - 2028: 300
- **Wafer Reclaim Capacity:**
  - 2024: 160 K/M
  - 2025: 210 K/M
  - 2026: 250 K/M
  - 2027: 300 K/M ???
- **Equipment installs:**
  - Taiwan
  - China
  - Korea
  - SGP/MY
  - Europe
  - USA

# Excellent Production Support

## TSMC 2024 Outstanding Suppliers Award



<https://pr.tsmc.com/english/news/3192>

## **2 Hybrid Revenue Model – Stability with Growth Leverage:**

- **Representative/Agent business – asset-light, margin supportive, stable**
- **Wafer Reclaim – recurring, stable**
- **Equipment Manufacturing – growth-driven, AI strong demand upside**

**This structure provides:**

- **Base recurring revenue**
- **Growth upside from AI demand**
- **Lower volatility vs. pure equipment peers**

**Positioning: Our hybrid model combines structural stability with AI-driven growth leverage.**



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Thank You!

<https://www.scientech.com.tw>